

Title (en)

EPOXY RESIN CURING AGENT, METHOD FOR PRODUCING THE SAME, AND EPOXY RESIN COMPOSITION

Title (de)

EPOXIDHARZHÄRTER, HERSTELLUNGSVERFAHREN DAFÜR UND EPOXIDHARZZUSAMMENSETZUNG

Title (fr)

AGENT DE DURCISSEMENT POUR RÉSINES ÉPOXY, SON PROCÉDÉ DE PRODUCTION ET COMPOSITION DE RÉSINE ÉPOXY

Publication

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Application

**EP 08860517 A 20081208**

Priority

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- JP 2007322329 A 20071213

Abstract (en)

[origin: EP2226347A1] It is an object of the present invention to provide an epoxy resin curing agent which has a favorable pot life and good storage stability as a curing agent for epoxy resins and from which an epoxy resin cured product having good water resistance and hardness is obtained through curing. The present invention is an epoxy resin curing agent containing a secondary or tertiary branched thiol compound having a substituent on a carbon atom at the  $\pm$ -position to a thiol group, and is also an epoxy resin composition comprising a polyvalent epoxy compound and the epoxy resin curing agent.

IPC 8 full level

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